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APPLICATION NO.	FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO. CONFIRMATION		
10/047,681	01/14/2002		Kuan-Sheng Hsieh	JCLA7793 5281		
7590 03/16/2004		EXAMINER		INER		
J.C. Patents, Inc.				MITCHELL, JAMES M		
Suite 250 4 Venture				ART UNIT	PAPER NUMBER	
Irvine, CA 92	2618			2827		
				DATE MAILED: 03/16/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application	No.	Applicant(s)				
		10/047,681		HSIEH, KUAN-SHENG				
	Office Action Summary	Examiner		Art Unit				
		James M. M	litchell	2827				
	The MAILING DATE of this communication	on appears on the c	over sheet with the c	orrespondence ad	dress			
THE I - Exter after - If the - If NO - Failui Any r	ORTENED STATUTORY PERIOD FOR F MAILING DATE OF THIS COMMUNICAT sions of time may be available under the provisions of 37 C SIX (6) MONTHS from the mailing date of this communicat period for reply specified above is less than thirty (30) days period for reply is specified above, the maximum statutory to reply within the set or extended period for reply will, by peply received by the Office later than three months after the d patent term adjustment. See 37 CFR 1.704(b).	ION. CFR 1.136(a). In no evention. s, a reply within the statuto period will apply and will o statute, cause the applic	, however, may a reply be tim ory minimum of thirty (30) days expire SIX (6) MONTHS from ation to become ABANDONE	nely filed s will be considered timely the mailing date of this co				
Status								
1)🖂	Responsive to communication(s) filed on	08 December 200	<u>)3</u> .					
2a) <u></u> ☐	This action is FINAL . 2b)⊠ This action is non-final.							
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Dispositi	on of Claims							
5)□ 6)⊠ 7)□								
Applicati	on Papers							
10)⊠	The specification is objected to by the Exa The drawing(s) filed on <u>14 January 2002</u> in Applicant may not request that any objection in Replacement drawing sheet(s) including the co The oath or declaration is objected to by the	is/are: a)⊠ accept to the drawing(s) be correction is required	held in abeyance. See I if the drawing(s) is obj	e 37 CFR 1.85(a). jected to. See 37 CF	FR 1.121(d).			
Priority u	nder 35 U.S.C. § 119							
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 								
Attachment	• •	_	. □ I	(DTO 442)				
2) Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-94 nation Disclosure Statement(s) (PTO-1449 or PTO/5 No(s)/Mail Date <u>12/8/2003</u> .	SB/08) 5	Pi Interview Summary Paper No(s)/Mail Da Notice of Informal P Other:	ate	D-152)			

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DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-3 are rejected under 35 U.S.C. 102(b) as being anticipated by Hayes et al. (US 5,736,074).

Hayes (Col. 8-9, Lines 55-26) discloses a bonded anisotropic conductive film, comprising: a resin material (109); and a plurality of conductive particles (108) dispersed in the resin material, wherein one or-more conductive particle includes a solder material covered with an outermost flux layer; wherein the solder material includes lead-tin alloy and encapsulates an inherent conducive bead (middle portion of solder bead).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 18 is rejected under 35 U.S.C. 103(a) as being unpatentable over Hozumi (JP406275123A) as applied to claim 1 and further in combination with Akram et al. (US 6,492,738).

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Hozumi does not appear to show that the polymer is a thermosetting resin.

However, Akram (Col. 5, Lines 46-48) utilizes a polymer thermosetting resin.

It would have been obvious to one of ordinary skill in the art to incorporate a thermosetting polymer resin around the particles of Hayes in order to provide a polymer as required by Hayes (109).

Claims 4-6, and 8-12, 14-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hozumi (JP406275123A) in combination with Hayes et al. (US 5,736,074).

Hozumi (Fig 4, 6, 8, 13b) disclose a bonded anisotropic conducive film, ACF, comprising: a thermal set (Abstract) plastic material (via capable of being molded) capable of hardening at a first temperature; and a plurality of conductive particles forming within the plastic material (Fig 6) wherein each conductive particle has a gold conductive bead (8; Jap. Par. 0022), a bonding layer (10, via bonded to 11) and an insulation layer (11), wherein the bonding layer is comprised of a conductive material and forms a spherical structure that covers the surface of the conductive bead, such that the bonding layer includes a conductive bead, and wherein the insulating layer forms an outermost covering laver of each of said conductive bead, and wherein the bonding layer inherently melts at a second temperature (via metal) and the second temperature is higher than the first temperature; and a flip chip package having a bonded ACF inherently inserted (via its physically between) between a silicon chip (14; Jap. Par. 0039) with a plurality of first contact points (9) and a carrier ("substrate"; 15)

that has a plurality of second contact points (9) that form a common metallic bond through the bonding layer of conductive particles within the bonded ACF.

Hozumi does not appear to disclose that the bonding layer comprises lead-tin.

However Hozumi discloses the same invention except that bonding layer is Au instead of lead-tin, Hayes (Col. 8-9, Lines 55-26) shows that lead-tin and Au are equivalent metallic a materials known in the art known in the art to form conductive spheres. Therefore, because the two metal are art recognized equivalents at the time the invention was made, one of ordinary skill in the art would have found it obvious to substitute lead-tin for gold to form conductive spheres.

Allowable Subject Matter

Claim 19 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The following is a statement of reasons for the indication of allowable subject matter: the prior art does not disclose or make obvious forming a conductive particle including a gold conductive bead encapsulated in solder with a flux covering the outermost layer dispersed in a resin including all the limitations of the independent claim. While Hayes discloses the use of both gold and solder as a conductive sphere, it explicitly discloses that the sphere is **one** material in contrast to applicant's invention that claims the sphere is gold encapsulated by solder.

Response to Arguments

Applicant's arguments with respect to claims have been considered but are moot in view of the new ground(s) of rejection.

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Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James M. Mitchell whose telephone number is (571) 272-1931. The examiner can normally be reached on M-F 6:30-3:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kamand Cuneo can be reached on (571) 272-1957. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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